Talaria TWO modules have thermal ground pads placed in the middle of the footprint. These modules should be grounded through four vias in each PAD. The size of each pad is 1.4mm x 1.9mm. The size of the via is 12mils. Figure 30 shows the layout and via pattern for thermal conduction.

A picture containing text, circuit, electronics

Description automatically generated

Figure 30: Thermal ground pads